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## EUROPEAN PATENT APPLICATION

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- (1) Applicant: KABUSHIKI KAISHA TOSHIBA 72. Horikawa-Cho Salwal-ku Kawasaki-shi Kanagawa-ken(JP)
- ② Inventor: Nagano, Junya, c/o Intellectual Property Division Kabushiki Kalsha Toshiba, 1-1 Shibaura 1-chome Minato-ku, Tokyo 105(JP)
- Representative: Weldren, Robin Michael et al Marks & Clerk, 57-60 Lincoln's Inn Fields London WC2A SLS(GB)
- Samiconductor device having an interconnecting circuit board and method for manufacturing
- A semiconductor device having an interconnecting circuit board comprises an island (20) formed in a predetermined plane, a semiconductor chip (21) disposed on the island (20) and having a plurality of electrically connecting electrode pads (22), an interconnecting circuit board (23) disposed on the semiconductor chip (20) and having an electrically conductive pattern (27), a plurality of inner leads (25) disposed around the island (20), a first electrically connecting wire (28c) connecting the electrically conductive pattern (27) and one (22b) of the plurality of electrically connecting electrode pads (22), and a second electrically connecting wire (26a,26b) connecting the electrically conductive pattern (27) and one (25a) of the inner leads (25).



